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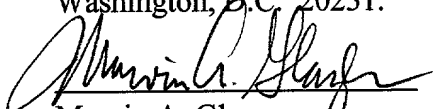
Docket No. 5833-A-13

Date January 22, 2001

Express Mail Mailing Label No. EL148762168US

Date of Deposit: January 22, 2001

I hereby certify that this paper or fee is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to the Commissioner of Patents and Trademarks, Washington, D.C. 20231.

  
Marvin A. Glazer

January 22, 2001  
Date

Box PATENT APPLICATION  
Honorable Commissioner for Patents  
Washington, D.C. 20231

Sir:

Transmitted herewith for filing is the patent application of

Inventors: Jamin Ling and Dave Charles Stepniak

For: "ELECTROLESS Ni/Pd/Au METALLIZATION STRUCTURE FOR COPPER INTERCONNECT SUBSTRATE AND METHOD THEREFOR"

Enclosed are:

- X 1 sheet of informal drawings
- X Declaration and Power of Attorney
- X Specification (incl. claims and abstract) 13 pages.

X Assignment

X Form PTO-1595 Recordation Form Cover Sheet

CLAIMS AS FILED

Total  
Claims                      24 - 20 = 4 x \$18.00 = \$ 72.00

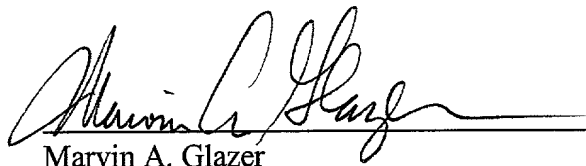
Independent  
Claims                      2 - 3 = 0 x \$80.00 = -0-

Basic Fee: \$710.00

Total Filing Fee: \$782.00

X The Commissioner is hereby authorized to charge any additional fees which may be required by this paper to Deposit Account No. 03-0088 and to credit any overpayment to this Deposit Account. Two (2) duplicate copies of this sheet are enclosed.

X A check in the amount of \$822.00 to cover the filing fee and the recordation fee (if needed) is enclosed.



Marvin A. Glazer  
Reg. No. 28,801